

12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20230502000.1 Qualification of CARZ as an alternate Assembly site for the DAC7551IDRNR/T Change Notification / Sample Request

Date: May 04, 2023

To: TOKYO ELECTRON DEVICE (DSTR) PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If additional data is required, requests must be received within **30** days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the PCN Team (<u>PCN www admin team@list.ti.com</u>). For sample requests or sample related questions, contact your local Field Sales Representative.

Sincerely,

PCN Team SC Business Services

20230502000.1 Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty four (24) months. The corresponding customer part number is also listed, if available.

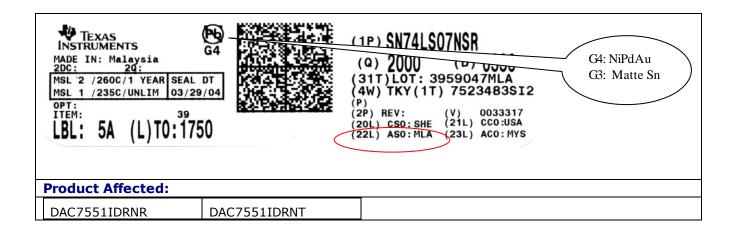
DEVICEDAC7551IDRNT
DAC7551IDRNR

CUSTOMER PART NUMBER

null null

Technical details of this Product Change follow on the next page(s).

PCN Number: 20230		0230502	0502000.1						PCN D	ate:	May 04, 2023	
			CARZ as an alternate Assembly site for the									
Customer Contact: PCN Manager Dept: Quality Services												
			Aug 1,	Aug 1, 2023		Sample Reque accepted ui				1 11100 / /11/3		
*Sample requests received after June 2, 2023 will not be supported.												
Change Type:												
Assembly Site				_	Design			<u> </u>	Wafer Bump Site			
Assembly Process					Data Sheet			<u> </u>	Wafer Bump Material			
Assembly Materials					Part number change				Wafer Bump Process Wafer Fab Site			
Mechanical Specification				_	Test Site			H	Wafer Fab Site Wafer Fab Materials			
☐ Packing/Shipping/Labeling			ig [L		Test Process L			Ħ	Wafer Fab Process			
	PCN Details											
Description	of Char	nge:										
Texas Instruments Incorporated is announcing the qualification of CARZ as an additional Assembly site for the DAC7551IDRNR/T. Construction differences are as follows:												
						AP3			CARZ			
Mount Compound			und	S	ID#1	D#101319028 SID#443			156			
Mold Compound			nd	S	ID#1	01375248		SID#444567				
Reason for C		:										
Supply contin												
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):												
None												
Impact on Environmental Ratings												
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.												
RoHS		REACH			Green Status					C 62474		
No Change		No Chan	No Change		☑ No Change			\boxtimes	☑ No Change			
Changes to product identification resulting from this PCN:												
Assembly Site As		Asseml	sembly Site Origin (22L)			Assembly Country Coc (23L)				Ass	embly City	
AP3	AP3				PHL					Binan		
CARZ			CSZ			CHN				Jiangsu		
Sample produ	ıct shinı	oina lahe	el (not	actual nr	oduc	t label)						





TI Information Selective Disclosure

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	QBS Product/Process/PAckage Reference: DAC7551ZTDRNRQ1	QBS Process Reference: DAC7551TDRNRQ1
PC	Preconditioning Level 2	Level 2-260C	3/1464/0	1/255/0
ED	Electrical Distributions	Per Datasheet Parameters	3/90/0	1/30/0
HAST	Biased HAST, 110C/85%RH	264 Hours	3/231/0	-
HAST	Biased HAST, 130C/85%RH	96 Hours	-	1/77/0
AC	Autoclave 121C	96 Hours	3/231/0	1/85/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	-
HTSL	High Temp Storage Bake 150C	1000 Hours	1/77/0	-
HTOL	Life Test, 125C	1000 Hours	1/77/0	-
HTOL	Life Test, 125C	408 Hours	2/154/0	1/77/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	1/800/0
HBM	ESD - HBM	2000 V	-	1/3/0
HBM	ESD - HBM	4000 V	1/3/0	-
CDM	ESD - CDM	750 V	-	1/3/0
CDM	ESD - CDM	1500 V	1/3/0	-
LU	Latch-up	(per JESD78)	1/6/0	1/6/0
PD	Physical Dimensions	Cpk>1.67	3/30/0	1/30/0
SD	Surface Mount Solderability	Pb	1/15/0	1/22/0
SD	Surface Mount Solderability	Pb Free	1/15/0	1/22/0
WBP	Wire Bond Pull	Wires	3/90/0	1/30/0
WBS	Wire Bond Shear	Wires	3/90/0	1/30/0

⁻ QBS: Qual By Similarity

- Qual Device DAC7551IDRNR is qualified at LEVEL2-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- $The following are equivalent \ HTSL \ options \ based \ on \ an \ activation \ energy \ of \ 0.7eV: \ 150C/1k \ Hours, \ and \ 170C/420 \ Hours$
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

TI Qualification ID: 20200811-135710

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail				
WW Change Management Team	PCN www admin_team@list.ti.com				

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